FAIRCHILD

SEMICONDUCTOR ™

September 1983
Revised January 2005

MM74HC86
Quad 2-Input Exclusive OR Gate

General Description

The MM74HC86 EXCLUSIVE OR gate utilizes advanced silicon-gate CMOS technology to achieve operating speeds similar to equivalent LS-TTL gates while maintaining the low power consumption and high noise immunity characteristic of standard CMOS integrated circuits. These gates are fully buffered and have a fanout of 10 LS-TTL loads. The 74HC logic family is functionally as well as pin out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

■ Typical propagation delay: 9 ns
■ Wide operating voltage range: 2–6V
■ Low input current: 1 µA maximum
■ Low quiescent current: 20 µA maximum (74 Series)
■ Output drive capability: 10 LS-TTL loads

Ordering Code:

Order Number	Package Number	Package Description
MM74HC86M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC86MX_NL	M14A	Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC86SJ	M14D	Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC86MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC86N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
MM74HC86NX_NL	N14A	Pb-Free 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

Connection Diagram

Pin Assignments for DIP, SOIC, SOP and TSSOP

Top View
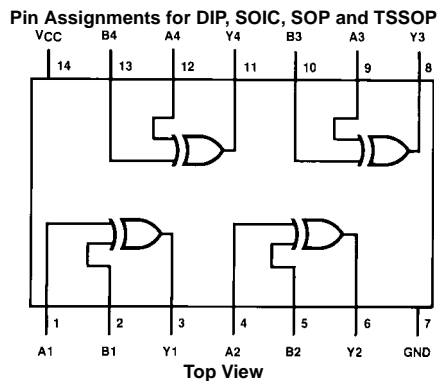
Truth Table

Inputs		Outputs
A	**B**	**Y**
L	L	L
L	H	H
H	L	H
H	H	L

$Y = A \oplus B = \overline{A} B + A \overline{B}$

MM74HC86

Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L)	
(Soldering 10 seconds)	260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage	0	V_{CC}	V
(V_{IN}, V_{OUT})			
Operating Temperature Range (T_A)	−40	+85	°C
Input Rise or Fall Times			
(t_r, t_f) V_{CC} = 2.0V		1000	ns
V_{CC} = 4.5V		500	ns
V_{CC} = 6.0V		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

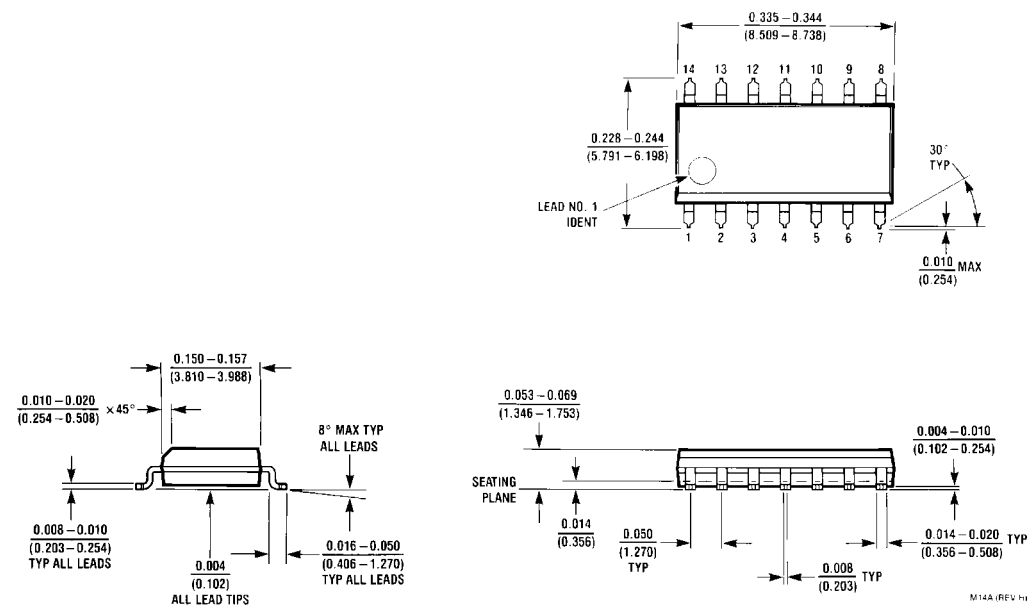**Note 3:** Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25°C$	$T_A = −40$ to $85°C$	$T_A = −55$ to $125°C$	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level		2.0V		1.5	1.5	1.5	V
	Input Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum LOW Level		2.0V		0.5	0.5	0.5	V
	Input Voltage		4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V_{OH}	Minimum HIGH Level	$V_{IN} = V_{IH}$ or V_{IL}					
	Output Voltage	|I_{OUT}| ≤ 20 μA	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or V_{IL}					
		|I_{OUT}| ≤ 4.0 mA	4.5V	4.2	3.98	3.84	3.7	V
		|I_{OUT}| ≤ 5.2 mA	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum LOW Level	$V_{IN} = V_{IH}$ or V_{IL}					
	Output Voltage	|I_{OUT}| ≤ 20 μA	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or V_{IL}					
		|I_{OUT}| ≤ 4.0 mA	4.5V	0.2	0.26	0.33	0.4	V
		|I_{OUT}| ≤5.2 mA	6.0V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND I_{OUT} = 0 μA	6.0V		2.0	20	40	μA

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

$V_{CC} = 5V$, $T_A = 25°C$, $C_L = 15$ pF, $t_r = t_f = 6$ ns

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL}, t_{PLH}	Maximum Propagation Delay		12	20	ns

AC Electrical Characteristics

$V_{CC} = 2.0V$ to $6.0V$, $C_L = 50$ pF, $t_r = t_f = 6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25°C$		$T_A = -40$ to $85°C$	$T_A = -55$ to $125°C$	Units
				Typ	Guaranteed Limits			
t_{PHL}, t_{PLH}	Maximum Propagation Delay		2.0V	60	120	151	179	ns
			4.5V	12	24	30	36	ns
			6.0V	10	20	26	30	ns
t_{TLH}, t_{THL}	Maximum Output Rise and Fall Time		2.0V	30	75	95	110	ns
			4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		25				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.
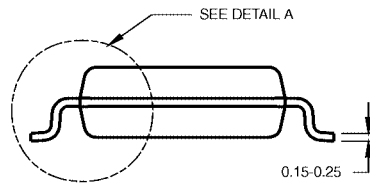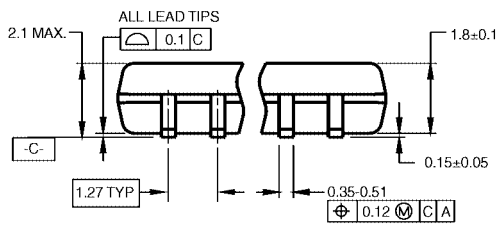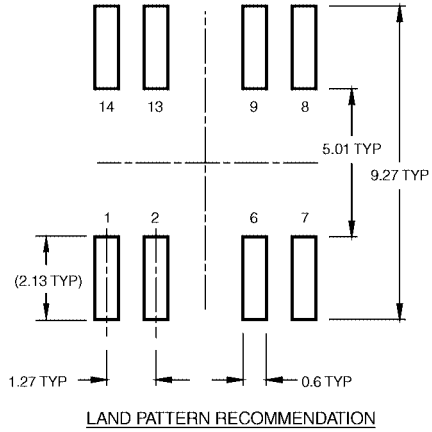
Physical Dimensions inches (millimeters) unless otherwise noted

$\dfrac{0.335 - 0.344}{(8.509 - 8.738)}$

14 13 12 11 10 9 8

$\dfrac{0.228 - 0.244}{(5.791 - 6.198)}$

LEAD NO. 1
IDENT

1 2 3 4 5 6 7

30°
TYP

$\dfrac{0.010}{(0.254)}$ MAX

$\dfrac{0.150 - 0.157}{(3.810 - 3.988)}$

$\dfrac{0.010 - 0.020}{(0.254 - 0.508)}$ × 45°

8° MAX TYP
ALL LEADS

$\dfrac{0.008 - 0.010}{(0.203 - 0.254)}$
TYP ALL LEADS

$\dfrac{0.004}{(0.102)}$
ALL LEAD TIPS

$\dfrac{0.016 - 0.050}{(0.406 - 1.270)}$
TYP ALL LEADS

$\dfrac{0.053 - 0.069}{(1.346 - 1.753)}$

$\dfrac{0.004 - 0.010}{(0.102 - 0.254)}$

SEATING
PLANE

$\dfrac{0.014}{(0.356)}$

$\dfrac{0.050}{(1.270)}$
TYP

$\dfrac{0.008}{(0.203)}$ TYP

$\dfrac{0.014 - 0.020}{(0.356 - 0.508)}$ TYP

M14A (REV H)

14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M14A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

10.2±0.1
-A-

1.1 TYP

14   8

7.8

5.3±0.1
-B-

3.9

⌂ 0.2 C B A
ALL LEAD TIPS

PIN #1 IDENT.

1   7

LAND PATTERN RECOMMENDATION

14   13   9   8

5.01 TYP

9.27 TYP

1   2   6   7

(2.13 TYP)

1.27 TYP   0.6 TYP

ALL LEAD TIPS

2.1 MAX.

⌂ 0.1 C

1.8±0.1

-C-

0.15±0.05

1.27 TYP   0.35-0.51

⊕ 0.12 Ⓜ C A

DIMENSIONS ARE IN MILLIMETERS

SEE DETAIL A

0.15-0.25

7° TYP

GAGE PLANE

0°-8° TYP   0.25

0.60±0.15

1.25

SEATING PLANE

DETAIL A

NOTES:
A. CONFORMS TO EIAJ EDR-7320 REGISTRATION,
   ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
   FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1
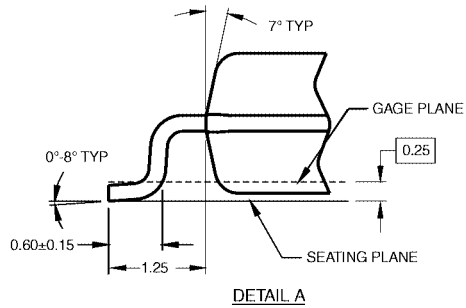
Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

5.0±0.1
-A-

0.43 TYP

14   8

6.4

3.2

4.4±0.1
-B-

0.2 C B A
ALL LEAD TIPS

1   7

PIN #1 IDENT.

7.72

4.16

1.78

0.65   0.42

LAND PATTERN RECOMMENDATION

1.2 MAX

ALL LEAD TIPS
0.1 C

0.90 +0.15 -0.10

-C-

0.10±0.05

0.65

0.19 - 0.30

⊕ 0.13Ⓜ A BⓈ CⓈ

SEE DETAIL A

0.09-0.20

12.00° TOP & BOTTOM

R0.09 min

GAGE PLANE

0.25

0°-8°

SEATING PLANE

0.6±0.1

R0.09 min

1.00

DETAIL A
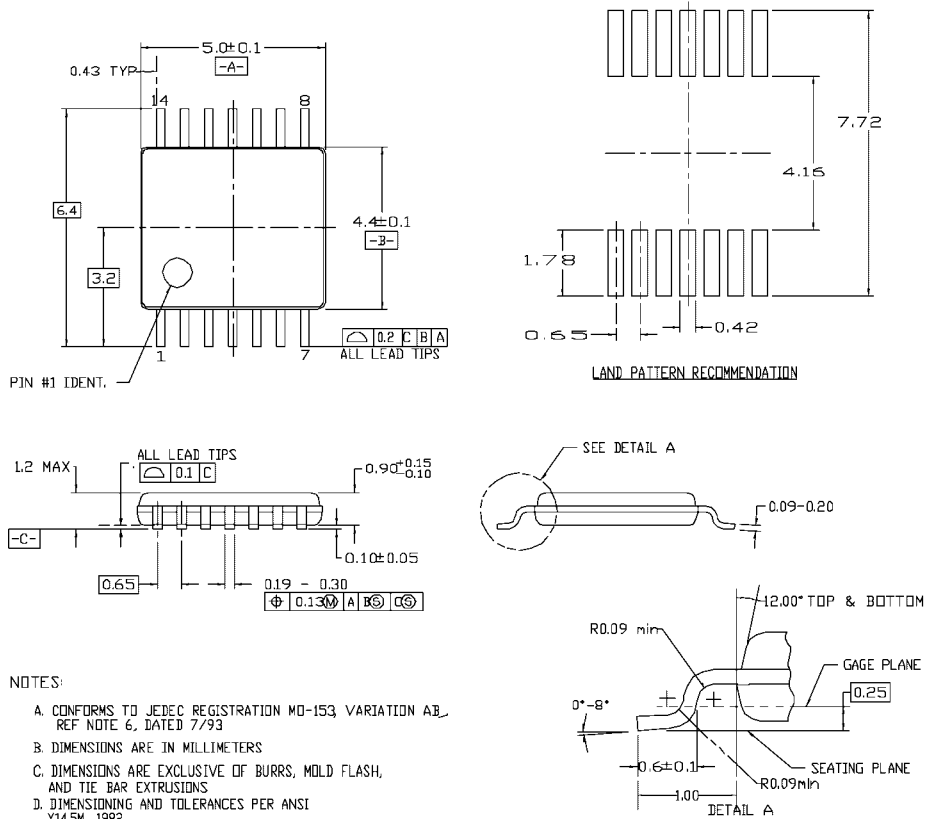
NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB,
   REF NOTE 6, DATED 7/93

B. DIMENSIONS ARE IN MILLIMETERS

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH,
   AND TIE BAR EXTRUSIONS

D. DIMENSIONING AND TOLERANCES PER ANSI
   Y14.5M, 1982

MTC14revD

14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

OPTION 1

OPTION 02
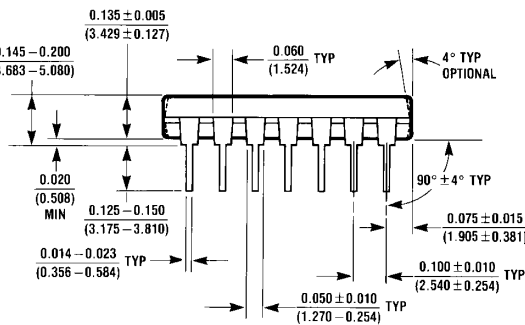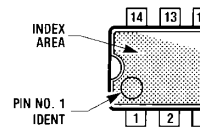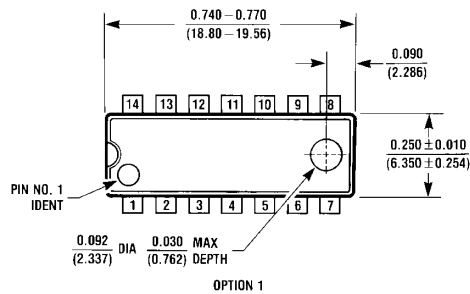
N14A (REV F)

14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N14A

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